WEICAI LCD/LED Bonding Machine

CR-880SH-19m

Precision Meets Performance Introducing the CR-880SH WEICAI COF Bonding Machine.

1. Model: CR-880SH WEICAI COF Bonding Machine.
2. Application: Designed for LCD, LED, and OLED screen repairs.
3. Technology: Utilizes advanced COF (Chip on Film) bonding technology.
4. Precision: Ensures accurate and reliable connections between flexible circuits and display panels.
5. Automation: Features automated alignment for consistency.
6. Controls: Equipped with adjustable temperature and pressure settings.
7. Interface: User-friendly and easy to operate.
8. Performance: Offers efficiency and consistency, ideal for professional use.

Device Name	Hot Press Machine
Device Model	CR-880SH-19M
Device Description	Screen repair equipment, LCD repair equipment, COF/TAB bonding equipment, etc.
Device Uses	This product is used in a variety of FPC, COF, TAB and LCD Panel and PCB combination bonding, is reflected in a variety of sizes LCD vertical, horizontal, vertical band, horizontal belt, black belt, black, colored thread, ribbon , multi-line, black, black and white, vertical half display,horizontal half breakdown maintenance.
Device Features	Single head ,single pneumatic device, single temperature control.
	Multi-speed pulse source design to meet the power requirements of diversified product pressure.
Applicable LCD Panel Specifications	15"-65"(Platform expandable)
Applicable LCD Panel Thickness	0.3MM-1.1MM[Single glass]
Panel Type	TFT

Bonding IC Number	One/PANEL
Bonding Direction	X or Y Unidirection
Bonding Head Size	Replaceable blade according to IC specifications (The original machine is equipped (50*1.4*10mm.
Production Beat	TAB，100pcs/H
Bonding Accuracy	±1.5µm (support 4K)
Highest Positioning Accuracy Setting	±0.5µm
Equipment requirements Work Environment	Clean, dust-free, clean room
Supply Pressure	0.1~0.7Mpa Dry air source
Power Supply	AC 220V±10%，50HZ，3500W
Pneumatic Device	Air TAC Original precision cylinder.

Pressure System	Pressure system parallel bar structure eliminates the weight of the indenter,pressure minimum accuracy can up to 0.1 KG,pressure components are using SMC precision components.
Heating Method	Pulse (rapid heating/cooling and auxiliary cooling)
Temperature Control System	Brand:Omron
	Adjustable temperature rise curve with high precision PID auto-tuning.
	The peak temperature : within +/-1degrees Celsius.
	Room temperature time to 180 degrees the response time within 2-3 seconds.

Hot Pressing Head	Material: Titanium Alloy
	Metal properties:SUS440C
	Origin: United States
	Plane precision (hot pressing surface) :0.001mm
	Plane thickness 0.5 (keep 3 times grinding)
Thermocouple Type	K type Original US OMEGA wire
Industrial Control Unit / Programme	Display control
Touch Unit	Display Control: Touch screen.
Image unit	COF counterpoint: Down counterpoint (Optical Path: Lens> Quartz> ITO Electrode> COF).
	PCB alignment:None (optional installation)
	Number of lens: 2
	Microscope: 200–300 continuous zoom
	COF Display: 19–inch HD
	PCB front camera:None (optional installation)
COF Trimming Unit	Origin: China
	Rail type: U–rail
	Accuracy:0.01
	Adjustable direction:X/Y/R
	R stroke: coarse adjustment 360 degrees, fine adjustment +/– 5 degrees.

COF fixture	COF mechanical clamping type ,Z-direction tilt radius micrometer finetuning.
Lens Spinner Unit	Control mode: X / Y / Z micrometer control
	Focus Adjustment: Manually adjust the focus.

Silicone / Teflon	Manual switching positio
LCD stage (platform)	Manual slide movement,self-contained vacuum adsorption device.
Bonding Head Alignment	The cylinder can be set to stop in any position in the upper and lower directions.
Control Method	Touch screen + button operation
Parameter Setting	Can store multiple sets of hot pressing parameters as needed.

Rated Voltage	AC 180-220V
Peak Power	400-1100W (can support 68X1.4X10 wide bonding head).
Maximum Power	1100W
Actual Power	580W
Body Size	1800X1200x1520mm(L*W*H)
Net Weight of Equipment	430KG
Number of Packages	2
Equipment Packaging	Wooden boxes, non-logs (material is glued board, no fumigation is required for export).
Package Size and Gross Weight	1260X950X1680mm（L*W*H）320Kz
	1970X540X960mm（L*W*H） 110KG

The following picture is the device after packaged.